

Q2 FY2021 (July – September, 2020) Financial Announcement

October 29, 2020

Agenda:

Q2 FY2021 Consolidated Financial Summary
 Yoshikazu Nunokawa, Corporate Director, Executive Vice President & General Manager





Forward Looking Statements

- Disclaimer regarding forward-looking statements Forward-looking statements with respect to TEL's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors, including the economic situation, semiconductor/FPD market conditions, intensification of sales competition, safety and product quality management, intellectual property-related risks, and impacts from COVID-19.
- Processing of numbers
 For the amount listed, because fractions are rounded down, there may be the cases where the total for certain account titles does not correspond to the sum of the respective figures for account titles. Percentages are calculated using full amounts, before rounding.
- Exchange risk In principle, export sales of Tokyo Electron's mainstay semiconductor and FPD production equipment are denominated in yen. While some settlements are denominated in dollars, exchange risk is hedged as forward exchange contracts are made individually at the time of booking. Accordingly, the effect of exchange rates on profits is negligible.

FPD: Flat panel display



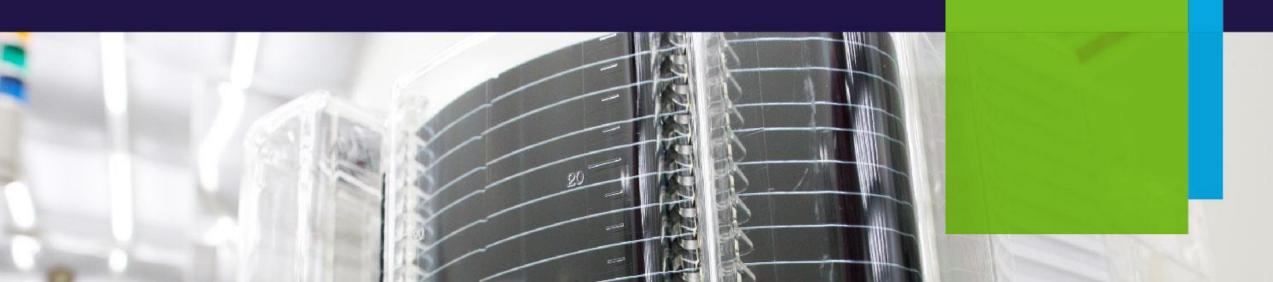
Q2 FY2021 Consolidated Financial Summary

October 29, 2020

Yoshikazu Nunokawa

Corporate Director, Executive Vice President & General Manager,

Global Business Platform Division



Financial Summary (H1)

(Billion Yen)

	FY2020		FY2021	YoY	(Reference)	
	H1	H2	H1	Change	FY2021 H1 estimates announced on June 18	
Net sales	508.4	618.8	668.1	+31.4%	620.0	
SPE	470.0	590.9	635.4	+35.2%	585.0	
FPD	38.3	27.7	32.6	-14.9%	35.0	
Gross profit Gross profit margin	204.5	247.4 40.0%	264.8 39.6%	+29.5% -0.6pts	248.0 40.0%	
SG&A expenses	102.0	112.5	117.3	+15.0%	121.0	
Operating income Operating margin	102.4	134.8 21.8%	147.4 22.1%	+43.9% +1.9pts	127.0 20.5%	
Income before income taxes	106.6	137.9	147.7	+38.5%	127.0	
Net income attributable to owners of parent	78.7	106.4	112.0	+42.3%	95.0	
R&D expenses	56.8	63.3	66.3	+16.7%		
Capital expenditures	29.6	25.0	28.2	-4.9%		
Depreciation and amortization	12.8	16.2	15.2	+18.9%		

^{1.} In principle, export sales of Tokyo Electron's mainstay semiconductor and FPD production equipment are denominated in yen. While some settlements are denominated in dollars, exchange risk is hedged as forward exchange contracts are made individually at the time of booking.



^{2.} Profit ratios are calculated using full amounts, before rounding.

Financial Summary (Quarterly)

(Billion Yen)

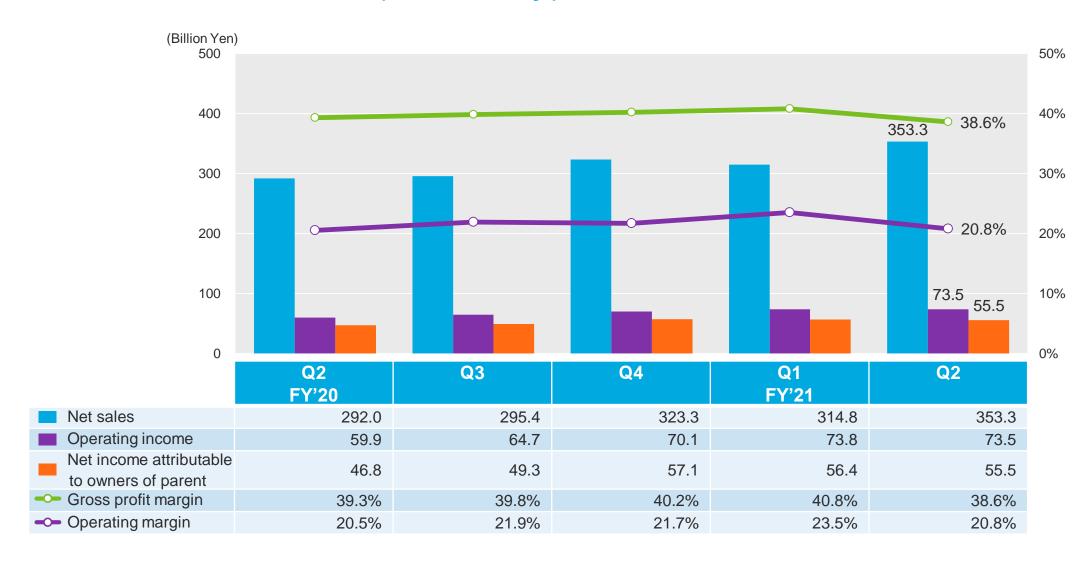
	FY2020			FY2		
	Q2	Q3	Q4	Q1	Q2	vs. Q1 FY2021
Net sales	292.0	295.4	323.3	314.8	353.3	+12.2%
SPE	271.8	282.0	308.9	303.7	331.6	+9.2%
FPD	20.1	13.3	14.3	11.0	21.6	+96.3%
Gross profit Gross profit margin	114.6 39.3%	117.5 39.8%	129.8 40.2%	128.4 40.8%	136.3 38.6%	+6.1% -2.2pts
SG&A expenses	54.7	52.8	59.7	54.6	62.7	+14.8%
Operating income Operating margin	59.9 20.5%	64.7 21.9%	70.1 21.7%	73.8 23.5%	73.5 20.8%	-0.4% -2.7pts
Income before income taxes	62.0	64.6	73.3	74.6	73.0	-2.2%
Net income attributable to owners of parent	46.8	49.3	57.1	56.4	55.5	-1.6%
R&D expenses	31.2	29.8	33.4	30.1	36.2	+20.2%
Capital expenditures	22.0	13.2	11.7	13.2	14.9	+12.6%
Depreciation and amortization	6.7	7.6	8.6	7.1	8.1	+13.3%

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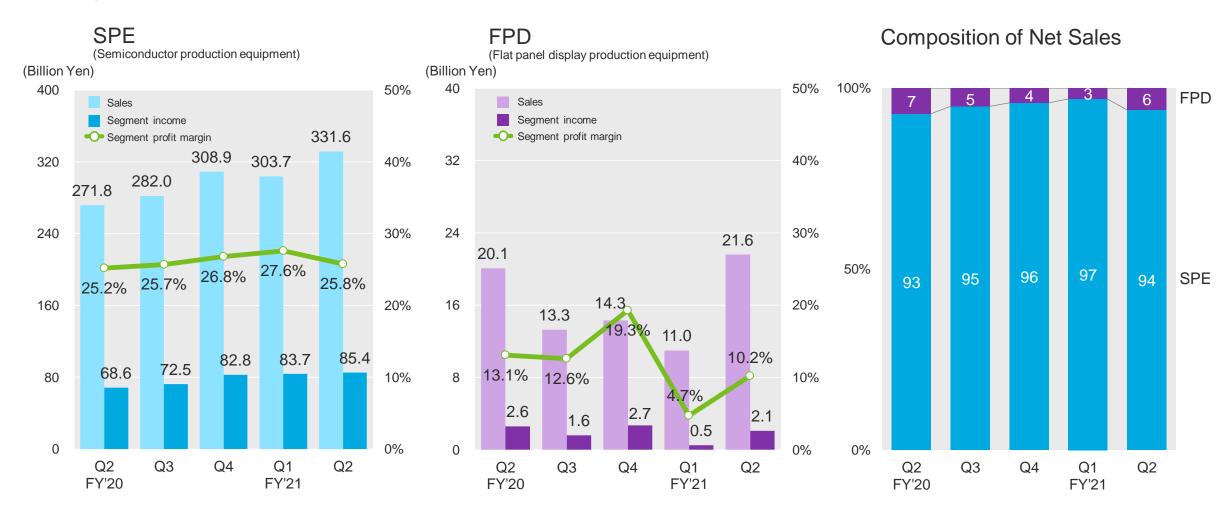


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Financial Performance (Quarterly)



Segment Information (Quarterly)



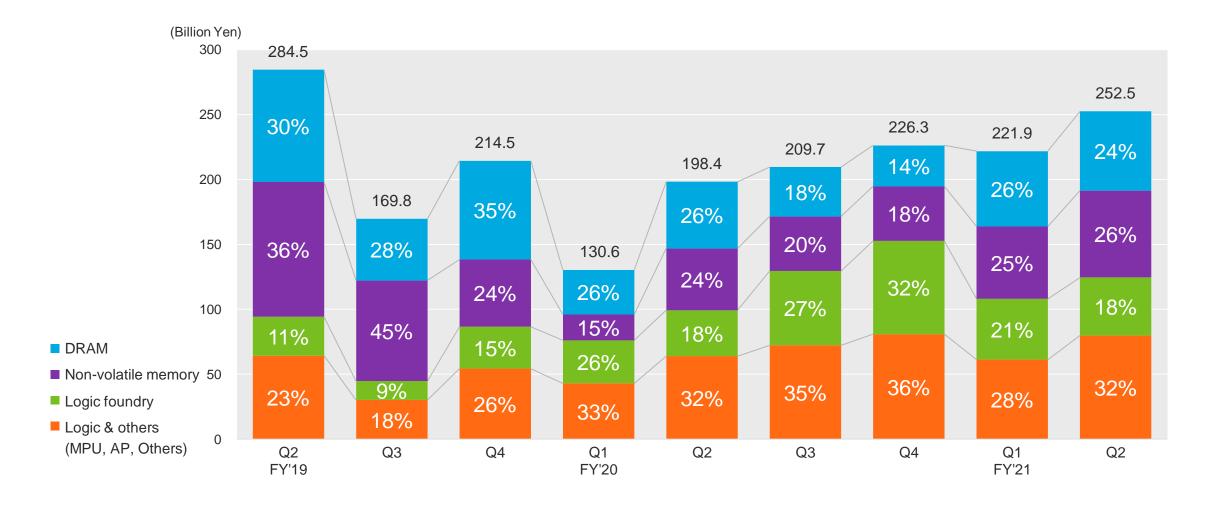
- 1. Segment income is based on income before income taxes.
- 2. R&D expenses such as fundamental research and element research, etc. and other general and administrative expenses are not included in the above reportable segments.
- 3. Composition of net sales figures is based on the sales to customers.

SPE Division: Sales by Region (Quarterly)





SPE Division: New Equipment Sales by Application (Quarterly)

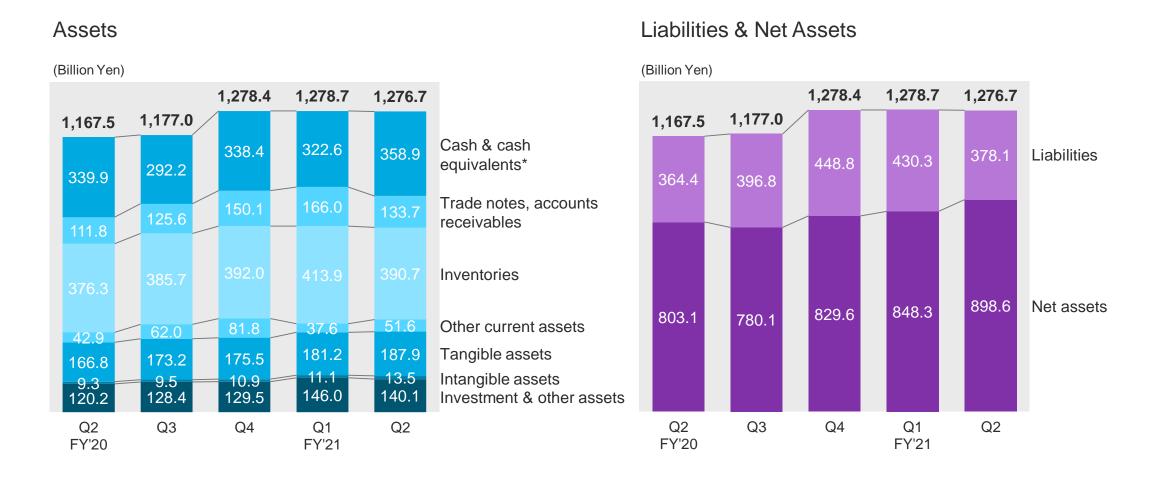


Field Solutions Sales (Quarterly)



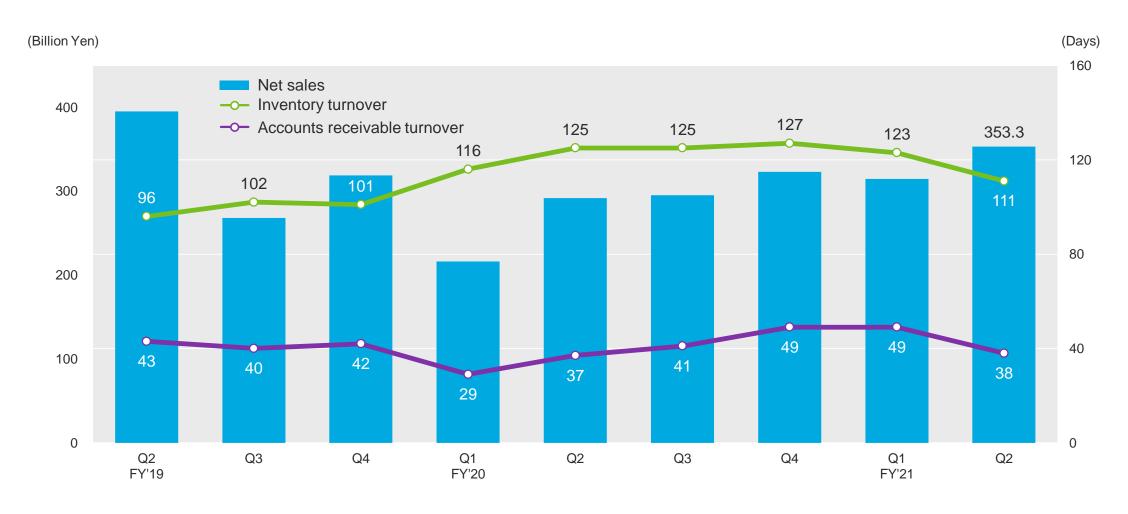


Balance Sheet (Quarterly)





Inventory Turnover and Accounts Receivable Turnover (Quarterly)



Turnover days = inventory or accounts receivable at the end of each quarter / last 12 months sales x 365



Cash Flow (Quarterly)



^{*1} Cash flow from investing activities excludes changes in time deposits and short-term investments.



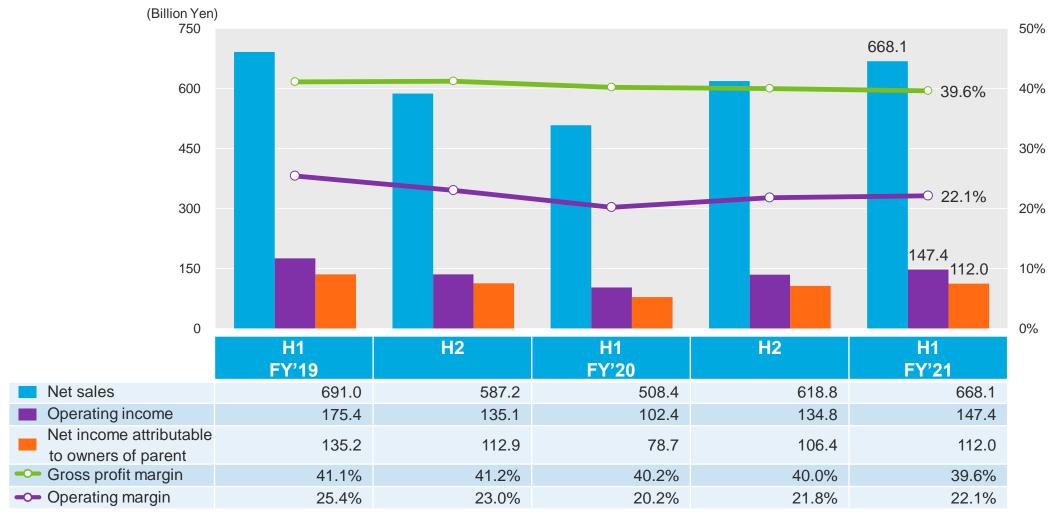
^{*2} Free cash flow = cash flow from operating activities + cash flow from investing activities (excluding changes in time deposits and short-term investments).

^{*3} Cash on hand includes cash and cash equivalents + time deposits and short-term investments with original maturities of more than three months.

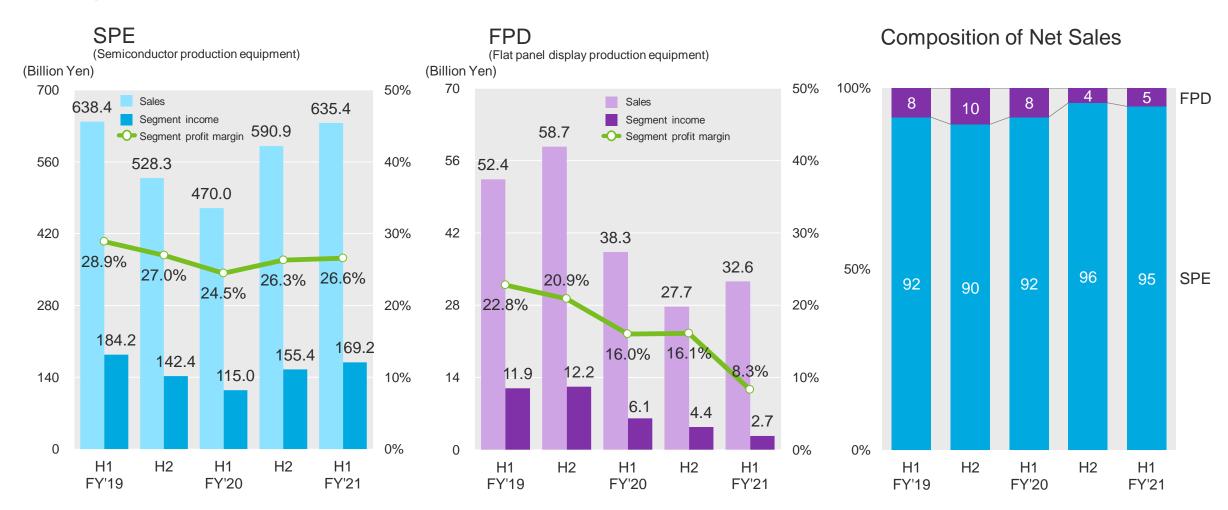
Appendix



Financial Performance (Biannually)



Segment Information (Biannually)



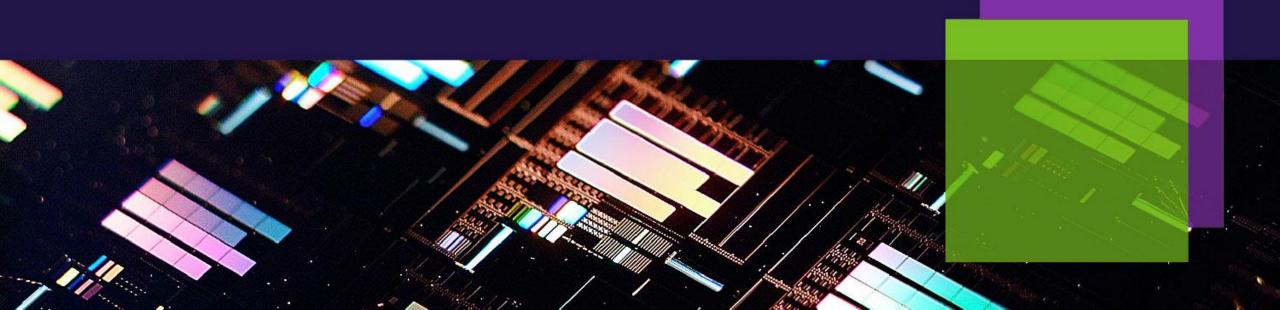
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Business Environment and Financial Estimates

October 29, 2020

Toshiki Kawai Representative Director, President & CEO



Business Environment (Outlook as of October 2020)

- WFE*1 capex Expecting CY2020 WFE market to grow more than 10% YoY to a record high
- ► FPD production equipment capex for TFT array process*2

 Continuing investment in large panels for TVs and a recovery in investment in OLED for mobile applications

 Expecting approx. 15% YoY growth in CY2020

TEL.

^{*1} WFE (Wafer fab equipment): The semiconductor production process is divided into front-end production, in which circuits are formed on wafers and inspected, and back-end production, in which wafers are cut into chips, assembled and inspected again. Wafer fab equipment refers to the production equipment used in front-end production and in wafer-level packaging production.
*2 TFT array process: The processes of manufacturing the substrates with the electric circuit functions that drive displays

CY'20 WFE Market and Business Opportunities by Application

- Logic/Foundry: At a high level, up YoY
 - Market environment: Firm demand for both leading-edge and matured technologies
 - Opportunities: Business expansion in more complex patterning processes
- DRAM: Steady YoY
 - Market environment: Approx. 80% of capex for 1Ynm generation and beyond
 - Opportunities: Adoption of new technologies that accommodate scaling
- Non-volatile memory: Approx. 50% increase YoY
 - Market environment: Accelerating investment for expanding production capacity.
 9X/12X generations to comprise over 80% of capex
 - Opportunities: Differentiation through high value-added etch and clean

FY2021 H1 Business Progress

- H1 sales and operating income both exceeded estimates. Sales rose
 31.4% YoY and operating income rose 43.9% YoY
 - Amid restrictions on travel overseas, accomplished equipment installations through collaboration between our plants and overseas subsidiaries
 - SPE business: Sales surpassed estimates on good progress in equipment installation and some customers having accelerated investment plans
 - FPD business: Started recovering in Q2 on progress in equipment installation
 - Field Solutions: Parts and services sales rose on high fab utilization rate by customers and optimization of inventory at our local subsidiaries
- New production buildings began operation at both the Tohoku and Yamanashi plants

FY2021 Financial Estimates



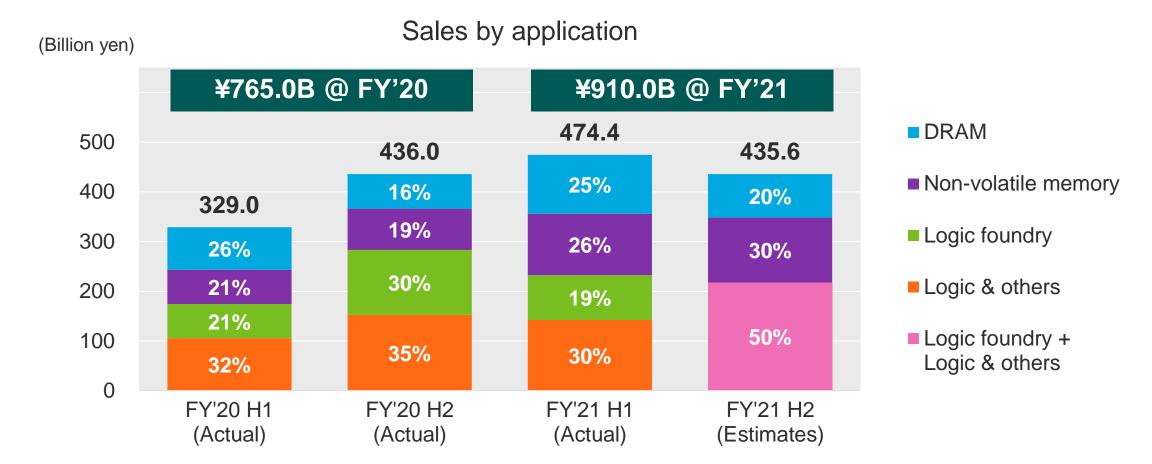
Revision of FY2021 Financial Estimates

(Billion yen)

		FY2021 (Estimates)						
	FY2020 (Actual)	1 st half	2 nd half	Full year		Full year		
		Actual	New estimates	New estimates	Adjustments*1	YoY change		
Net sales	1,127.2	668.1	631.8	1,300.0	+20.0	+15.3%		
SPE	1,060.9	635.4	584.5	1,220.0	+20.0	+15.0%		
FPD	66.0	32.6	47.3	80.0	0	+21.0%		
Gross profit Gross profit margin	451.9 40.1%	264.8 39.6%	258.1 40.9%	523.0 40.2%	+3.0 -0.4pts	+71.0 +0.1pts		
SG&A expenses	214.6	117.3	124.6	242.0	-3.0	+27.3		
Operating income Operating margin	237.2 21.0%	147.4 22.1%	133.5 21.1%	281.0 21.6%	+6.0 +0.1pts	+43.7 +0.6pts		
Income before income taxes	244.6	147.7	133.2	281.0	+6.0	+36.3		
Net income attributable to owners of parent	185.2	112.0	98.0	210.0	+5.0	+24.7		
Net income per share (Yen)	1,170.57	720.29	-	1,350.57	+32.47	+180.00		

Upwardly revised full year estimates to reflect good progress in H1 and additional investment by customers

FY2021 SPE Division New Equipment Sales Forecast



Expect FY2021 full year sales to rise approx. 20% YoY



FY2021 R&D Expenses, Capex Plan

- R&D Expenses ¥135.0B
 - Continue investing based on focus areas and sustainable growth
- Capex ¥56.0B
 - Actively invest in advanced technologies R&D and to meet increasing production
- Depreciation ¥38.0B

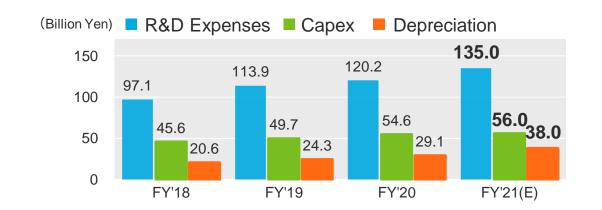
New production buildings (deposition systems, gas chemical etch systems, test systems)



Oshu City, Iwate Prefecture: approx. ¥13.0B construction cost (Began operation in July 2020)



Nirasaki City, Yamanashi Prefecture: approx. ¥13.0B construction cost (Began operation in August 2020)



Sapporo office (software development)



Sapporo City, Hokkaido Prefecture: (Scheduled to open in November 2020)

Miyagi Technology Innovation Center (etch systems)

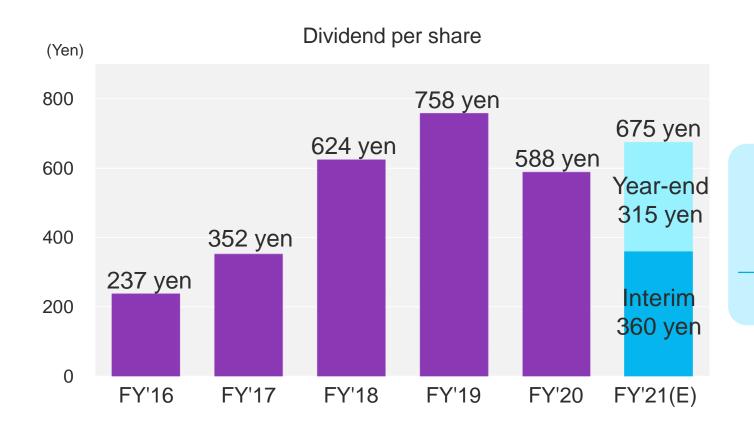


Kurokawa-gun, Miyagi Prefecture: approx. ¥7.0B construction cost (Completion scheduled for September 2021)

Planning record investment in R&D and capex to realize future growth



FY2021 Dividend Forecast



TEL shareholder return policy

Dividend payout ratio: 50%

Annual DPS of not less than 150 yen

We will review our dividend policy if the company does not generate net income for two consecutive fiscal years

We will flexibly consider share buybacks

Expect to pay DPS of 675 yen, in-line with 50% dividend payout ratio

